TRA	NSMITTA	Docket No. BUR920040182US1									
In Re Application Of:											
Fen Chen et al.											
Application No.		Filing OF DE	Examiner	Customer No.	Group Art Unit	Confirmation No.					
10/711,418		09/17/2004		30449	2812						
Title:											
NON-D	ESTRUCTI	IVE EVALUATION	OF MICROSTRUCTURE AND	INTERFACE I	ROUGHNESS O	F					
Address to: Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450											
			37 CFR 1.97(b)								
1. A The Information Disclosure Statement submitted herewith is being filed within three months of the filing of a national application other than a continued prosecution application under 37 CFR 1.53(d); within three months of the date of entry of the national stage as set forth in 37 CFR 1.491 in an international application; before the mailing of a first Office Action on the merits, or before the mailing of a first Office Action after the filing of a request for continued examination under 37 CFR 1.114.											
37 CFR 1.97(c)											
2.	2. The Information Disclosure Statement submitted herewith is being filed after the period specified in 37 CFR 1.97(b), provided that the Information Disclosure Statement is filed before the mailing date of a Final Action under 37 CFR 1.113, a Notice of Allowance under 37 CFR 1.311, or an Action that otherwise closes prosecution in the application, and is accompanied by one of:										
☐ the statement specified in 37 CFR 1.97(e);											
OR											
☐ the fee set forth in 37 CFR 1.17(p).											

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10/711,418	09/17/2004			30449	2812						
Title: NON-DESTRUCTIVE EVALUATION OF MICROSTRUCTURE AND INTERFACE ROUGHNESS OF											
Charge the amount of Sattached.											
Signature			Signature of Person Mailing Correspondence Betty Zuelsdorf								
	Printed Name of Person Sig		Турс	Typed or Printed Name of Person Mailing Certificate							
-		if paying by	Dated: 1	10/26/2004							
cc:											

Application Number Docket Number (Optional) BUR920040182US1 10/711,418 INFORMATION DISCLOSURE CITATION Applicant(s) Fen Chen et al. (Use several sheets if necessary) Filing Date Group Art Unit 09/17/2004 2812 **U.S. PATENT DOCUMENTS** •EXAMINER FILING DATE CLASS SUBCLASS DATE NAME INITIAL IF APPROPRIATE 6 U.S. PATENT APPLICATION PUBLICATIONS *EXAMINER FILING DATE SUBCLASS REF DOCUMENT NUMBER DATE NAME CLASS INITIAL IF APPROPRIATE FOREIGN PATENT DOCUMENTS Translation REF DOCUMENT NUMBER DATE COUNTRY CLASS SUBCLASS YES NO EP 1 376 680 A1 02.01.2004 **European Patent Office** OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.) USING THE TEMPERATURE COEFFICIENT OF THE RESISTANCE (TCR) AS EARLY RELIABILITY INDICATOR FOR STRESSVOIDING RISKS IN CU INTERCONNECTS, by A. von Glasow et al., Copyright 2003, pp. 126-131.

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP Section 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

EXAMINER

DATE CONSIDERED